

# RIGID PCB



## CAPABILITIES

Layers	1 - 62L	Min. Line Space	2.5 mil
Max Board Size	24" x 40"	Min. Mechanical Drill/Pad	6 mil   16 mil
Max Board Thickness	.315"	Min. Laser Drill/Pad	4 mil   10 mil
Min. Board Thickness	4L - 16 mil, 6L - 24 mil	PTH Dia. Tolerance	±3 mil
	8L - 40 mil, 10L - 48 mil	NPTH Dia. Tolerance	±1 mil
	12-16L - 63 mil	Hole Position Deviation	±3 mil
HDI Boards	Blind, Buried, Stacked Vias & ELIC	Outline Tolerance	±4 mil
Impedance Control	≤50 OHMS = ±5 OHMS	Solder Mask Dams	2 mil
	>50 OHMS = ±10%	Aspect Ratio Laser	1:1
Aspect Ratio Mechanical	Component	Flammability	94V-0
Min. Line Width	Component		

### SURFACE FINISHES

- Leaded HASL
- Lead Free HASL
- Immersion Gold (ENIG)
- Immersion Gold (ENEPIG)
- Immersion Silver
- Immersion Tin
- Hard Gold (Fingers)
- Selective Hard Gold
- Wire Bondable Soft Gold
- Flash Gold
- Carbon Ink
- OSP

### MATERIALS

- Standard Tg FR-4
- Mid Tg FR-4
- High Tg FR-4
- High Speed Materials
- Mixed Dielectric Constructions
- Halogen Free
- Polyimide

### CERTIFICATIONS

- UL
- ISO9001 (Quality System)
- IATF16949 (Automotive)
- ISO13485 (Medical)
- AS9100 (Aerospace)
- ISO14001 (Environmental)
- OHSAS18001 (Safety)
- ISO27001 (IP Protection)

### LEAD TIMES

Quick Turn, 5 - 10 Days from AsiaHigh Mix Low Volume  
Medium to High Volume  
*\* Technology level dependent*



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Production Base

No.94 building, Sai'er Kong blvd, Xiangshan Community, bao'an district, Shenzhen.

# FLEX PCB



## CAPABILITIES

Layers	1 - 12L	Outline (Laser) Tolerance	±2 mil
Max Board Size	15.75" x 23.5"	Cover Layer Dams	8 mil
Max Board Thickness	.040" without stiffener	Flammability	94V-0
Min. Board Thickness	4 mil	Impedance Control	≤50 OHMS = ± 5 OHMS >50 OHMS = ± 10%
Min. Line Width	2.5 mil		
Min. Line Space	2.5 mil		
Min. Mechanical Drill	4 mil		

\* Dynamic Flex & Flex-to-Install

### SURFACE FINISHES

- HASL
- ENIG
- ENEPIG
- Immersion Silver
- Immersion Tin
- Electrolytic Nickel/Gold
- Wire Bondable Soft Gold
- OSP

### MATERIALS

- Polyimide (adhesive, adhesiveless)
- PET/Polyester
- FR4/Polyimide/thick film stiffeners
- Material thickness:  
.5 mil through 2 mil

### CERTIFICATIONS

- UL
- ISO9001 (Quality System)
- IATF16949 (Automotive)
- ISO13485 (Medical)
- AS9100 (Aerospace)
- ISO14001 (Environmental)
- OHSAS18001 (Safety)
- ISO27001 (IP Protection)

### LEAD TIMES

Quick Turn, 5 - 10 Days from Asia  
 High Mix Low Volume  
 Medium to High Volume  
 \* Technology level dependent



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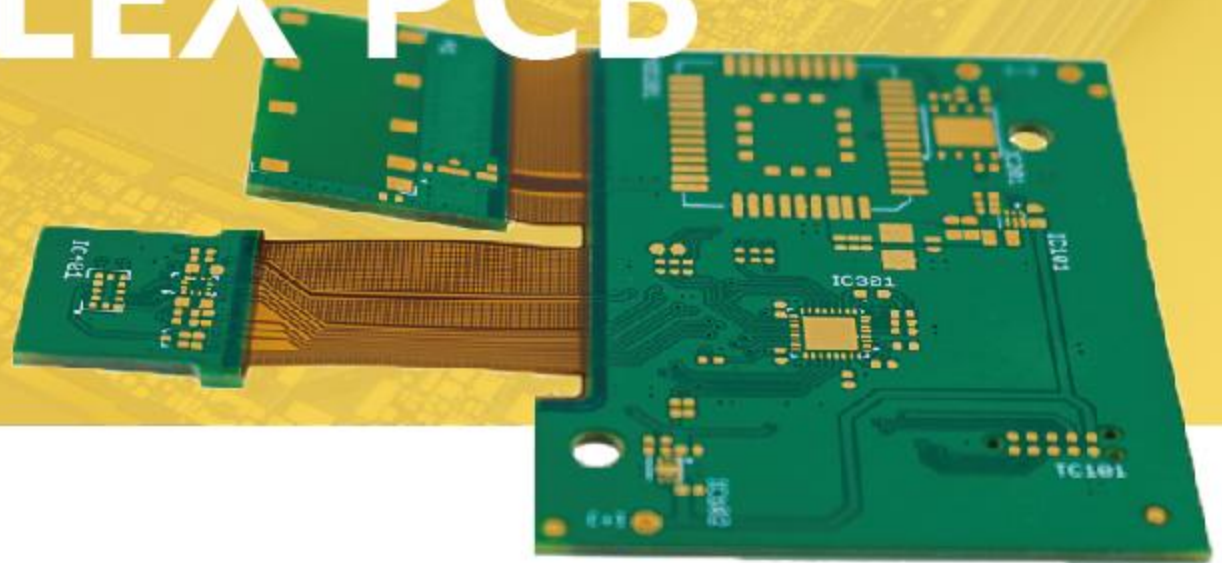
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# RIGID-FLEX PCB



## CAPABILITIES

Layers	2 - 40L	Max Buried Via	8 mil
Max Board Size	15.75" x 23.5"	PTH Dia. Tolerance	±3 mil
Board Thickness	.00788" - .1968"	NPTH Dia. Tolerance	±2 mil
Impedance Control	≤50 OHMS = ±5 OHMS >50 OHMS = ±10%	Hole Position Deviation	±3 mil
		Outline Tolerance	±4 mil
Min. Line Width	2.5 mil	Solder Mask Dams	3 mil
Min. Line Space	2.5 mil	Aspect Ratio Mechanical	20:1
Min. Mechanical Drill/Pad	6 mil   16 mil	Aspect Ratio Laser	1:1
Min. Laser Drill/Pad	4 mil   10 mil		

### SURFACE FINISHES

- HASL/LF HASL
- ENIG
- ENEPIG
- Immersion Silver
- Immersion Tin
- Electrolytic Nickel/Gold
- Wire Bondable Soft Gold
- OSP

### MATERIALS

- FR4 low/mid/high TG
- Polyimide
- Polyimide Film
- (adhesive, adhesiveless):  
Thicknesses - 1, 2, 3, 4, & 5 mil

### CERTIFICATIONS

- UL
- ISO9001 (Quality System)
- IATF16949 (Automotive)
- ISO13485 (Medical)
- AS9100 (Aerospace)
- ISO14001 (Environmental)
- OHSAS18001 (Safety)
- ISO27001 (IP Protection)

### LEAD TIMES

Quick Turn, 10 - 15 Days from Asia  
High Mix Low Volume  
Medium to High Volume  
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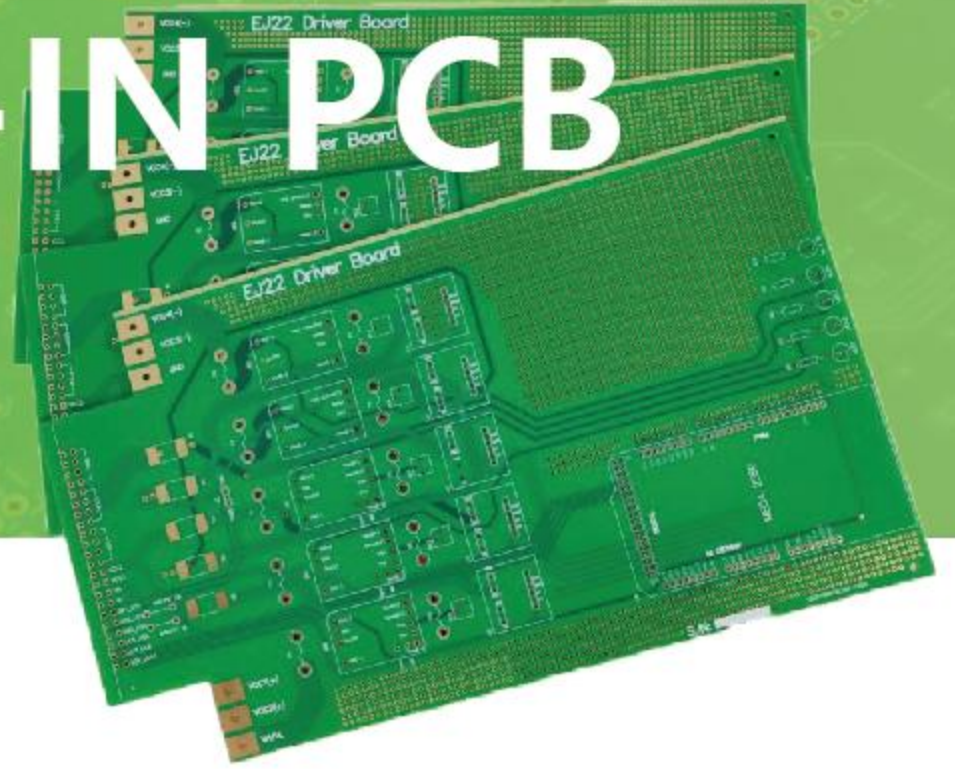
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# ATE/BURN-IN PCB



## CAPABILITIES

Layers	2 - 80L	Inner Layer Spacing Pad/Trace	1.5 mil
Max Board Size	15.75" x 30.0"	Aspect Ratio Mechanical	42:1
Board Thickness	.093" - .250"	Stub Drilling Max Depth	0.30 (.3mm pitch) - 0.130 (.5mm pitch)
DUT/Drill Pattern Pitch	.0118" (.3mm) minimum	Stub Drill Diameter	0.0079 (.3mm pitch) - 0.01 (.5mm pitch)
Min. Line Width	2.5 mil	Surface Finish	ENIG   ENIG   Hard Gold Selective Gold   Flash Gold
Min. Line Space	2.5 mil		
Min. Mechanical Drill/Pad	4 mil   10 mil	Impedance Control	≤50 OHMS = ±5 OHMS >50 OHMS = ±10%
Min. Laser Drill/Pad	3 mil   6 mil		

## SURFACE FINISHES

- HASL/LF HASL
- ENIG
- ENEPIG
- OSP

## MATERIALS

Standard FR-4  
(high Tg, high Td)

- Panasonic R-1755S
- MGC EL-190T
- Hitachi MCL-E-679W
- Hitachi MCL-E-679FJ
- Hitachi MCL-E-75G

Low Dk/Df for High Speed/  
High Frequency

- Panasonic R-5725 (Megtron4)
- Panasonic R-5775 (Megtron6)
- Panasonic R-5785(N) (Megtron7 LD)
- MGC EL-230T
- Hitachi HE-679G
- Hitachi HE-679GS
- AGC (Park Electrochemical) Meteorwave 4000
- Rogers RO4350B

## LEAD TIMES

Lead times vary widely depending on material selection and technology level. Lead time can be evaluated at time of quote.



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# SPECIALTY PCB



## CAPABILITIES

### METAL SUBSTRATE PCB

Aluminum Substrate, Copper Subs Aluminum Substrate and Copper Substrates	
Metal-Substrate Control Depth Capability (mm)	±0.05
Counter Bore Depth-Controlled Capability (mm)	±0.10
Maximum Copper Weight (OZ)	12

### SPECIAL PROCESSES

Heat Sink	Embedded Resistance
ViPPO	Embedded Capacitance
Resin Fill	Hybrid Lamination
[Conductive and Non-Conductive]	Micro-Via Copper Fill
Oversize Backplane	Heavy Copper UL - 60oz
Metal-Buried PCB	Back Drill

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### MATERIALS

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